INTEGRATED CIRCUIT CHIP PACKAGING PROCESS

ABSTRACT OF THE DISCLOSURE

An integrated circuit chip packaging process includes the steps of: (a) preparing a ceramic substrate having sub-substrates, each sub-substrate having connecting pads, and then attaching a respective die on each of the sub-substrates; (b) electrically connecting the dies at the sub-substrates to the pads; (c) putting the die-attached ceramic substrate in a cavity of a first die of a mold, and then closing a second die of the mold on the first die by the way of not contacting the second die to the substrate to form an enclosed mold cavity in the mold, and then filling a molten encapsulating material into the enclosed mold cavity to form a molding on the top side of the substrate so as to encapsulate the sub-substrates and the die at each the sub-substrate.

Figure : 1